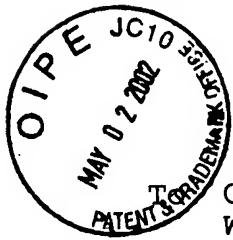


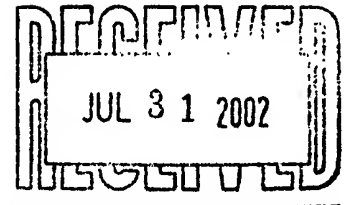
STATS-01-005



April 26, 2002

Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572  
20 McIntosh Drive  
Poughkeepsie, N.Y. 12603



Subject:

Serial No. 10/083,993 02/26/02

Jeffrey D. Punzalan et al.

GROUND PLANE FOR EXPOSED PACKAGE

Grp. Art Unit: 2811

#### INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation  
In An Application.

The following Patents and/or Publications are submitted  
comply with the duty of disclosure under CFR 1.97-1.99 and  
37 CFR 1.56. Copies of each document is included herewith.

#### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being  
deposited with the United States Postal Service as first class  
mail in an envelope addressed to: Commissioner of Patents and  
Trademarks, Washington, D.C. 20231, on April 29, 2002.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

*Stephen B. Ackerman* 4/29/02

U.S. Patent 6,300,673 to Hoffman et al., "Edge Connectable Metal Package," discloses a die attach paddle and ground plane for a package.

U.S. Patent 6,284,571 to Corisis et al., "Lead Frame Assemblies with Voltage Reference Plane and IC Packages Including Same," describes a structure for a die attach paddle and ground plane for a package.

U.S. Patent 6,096,163 to Wensel, "Method and Apparatus for Application of Spray Adhesive to a Leadframe for Chip Bonding," discloses a process for adhesives to leadframe.

U.S. Patent 5,434,750 to Rostoker et al., "Partially-Molded, PCB Chip Carrier Package for Certain Non-Square Die Shapes," discloses a leadframe design.

Sincerely,

A handwritten signature in black ink, appearing to read 'SBA', is written over the printed name.

Stephen B. Ackerman,  
Reg. No. 37761

